Rajshahi University of Engineering & Technology B.Sc. Engineering 3rd Year 6th Semester Examination, 2015 Department of Computer Science & Engineering Course Ma Computer Architecture Course No. CSE 603 Course Title: Computer Architecture Full Marks: 70 Time: THREE (03) hours

N.B:

Answer SIX questions taking THREE from each section. The questions are of equal value.

Use separate answer script for each section

SECTION A

SECTION A	
Y-1(a) What do you mean by the followings:	Marks O3
(b) Define (i) Multiprocessor Organization (ii) Cluster Computing (iii) VGA	06
port and (iv) HDMI port. (e) Explain the importance of a cache memory in Computer Architecture. (a) How does an ALU work? Discuss Booth's algorithm with necessary	02³3 04
 example. (b) Define (i) 1's compliment and (ii) 2's compliment for data processing. (c) Discuss the problem of sign magnitude representation of any number. (d) With necessary diagram, describe hardware implementation of unsigned binary multiplication. 	02 02 03 ² 5
Q.3(a) Draw the CPU structure and hence describe the functions of it in brief.(b) What do you mean by instruction cycle? With neat sketch, describe the	05 ³ 3 06
Q.4(a) What do you mean instruction pipelining: write the data and	0323
 (b) What are the differences between instruction level parallelism (ILP) and parallel processing? (c) Write down the necessary examples which show the advantages of ILP 	03
execution over sequential execution. (d) What are the ILP challenges to achieve parallelism?	02
SECTION B	
Q.5(a) Describe the different addressing modes with at least one example for	05%
each. (b) Briefly discuss the followings:	06
(i) Von Neumann Architecture and (ii) Flynn's Classical Taxonomy. 9:6(a) Describe briefly (i) SISD (ii) SIMD (iii) MISD and (iv) MIMD. (b) Briefly describe the functions of the main components of a computer	06 05 ² 3
system. \mathcal{Q} .7(a) What are the advantages of symmetric multiprocessor architecture over	04
(c) How pipelining is used to enhance performance in the coment of	04 03 ² 3
Q.8(a) What is effective address? Consider the instruction $[SI][BX]$, CL. If $[BX] = 0200H$, ALPHA = 08H, $[SI] = 1000H$ and $[DS] = 3000H$. Then calculate the effective address where the content of CL will	033
move in based Indexed addressing mode. (b) Briefly explain (i) Big-Endian and (ii) Little-Endian representation. (c) Justify your answer for the statement "RISC is better than CISC or vice versa".	04 04

Rajshahi University of Engineering & Lechnology

B.Sc. Engineering 3rd Year 6th Semester Experiments at 2011 Department of Computer Science & Lagineering Course no: CSE 603 Course Title: Computer Architecture N.B. Answer six questions, taking three from each section, Time: Three (03) hours The questions are of equal value. Use separate answer script for each section. SECTION-A Draw the high performance architecture of bus configuration. In the high performance architecture of bus configuration why the main memory is moved off of the local bus & placed onto a system bus? What technology is used to design power PC processors? List out four features 04 of this technology. CTT- 591 What is the main problem of Daisy Chaining Approach? Discuss it with proper 05 Q2. (a) figure. 5- 2 • (b) What are the key tasks for pnp automates? 04 (c) Draw the figure of PCI bus in desktop system. Draw a flow chart for cache read operation. - (n) 04 (b) Draw the block diagram PCI configuration in a typical multiprocessor system. 04 Since processor's I/O capability is different from the speed of the PCI bus how $3\frac{2}{3}$ they can be coupled together? What is address number? Represent the following equation by one and two address number Z=(A/B)/(C*D-E)Consider that five instructions to execute I_1 , I_2 , I_3 , I_4 and I_5 and each has I_5 steps I_5 , I_5 , I_6 , I_7 , I_8 , I_9 , of (i) pipelining (ii) super pipelining (iii) scalar pipelining. SECTION-B Choose which techniques (SISD, SIMD, MISD and MIMD) used for designing the followings and why? (i) uniprocessor (ii) vector processor (iii) Array Q5/(a)processor (iv) systolic array. (b) Draw the block diagram of a digital computer. 03 $2\frac{2}{3}$ (c) Describe the Von Neuman architecture. Q6. (a) Draw the memory organization of 512KB×1 dynamic memory chip. 04 (b) In control unit organization, what are the functions of control step counter, status flags & condition code? \$ - 558 (c) What is meant by microprogramming language, microinstruction and microprogram?_11-430 (b) Draw the block disconstruction with example (1) 04 (b) Draw the block diagram of microprogrammed control unit that allows 04 conditional branching. CH-431 02 (c) Explain indirect addressing. (d) What is byte addressability? What is RAID? Describe its key concepts. 02 What are the problems of RAID. Describe which RAID level is selected and why for the following conditions. 06 (i) When you want to transfer data parallelly by saving their parity. 3 (ii) When you want to save the parity of the datas in distributed location. (iii) When you want to avoid double disk failure.

Heaven's light is our guide

CF

Rajshahi University of Engineering & Technology
B Sc. Engineering 1th Year 6th Semester Examination, 2010
Department of Computer Science & Engineering
Course no: CSF 603 Course Title Computer Architecture
Full marks: 70 — Time: Three (03) hours

Full marks: 70 Time: Three (03) hours	
N.B. Answer six questions, taking three from each section	
The questions are of equal value Use separate answer script for each section.	
SECTION-A	02
Q1. (a) Draw and explain internal connection between processor and memory.	2
(b) What is address number? Show the execution of the instruction, Y=(\x113-C)/(D1) by using one address instruction	4 3
(c) Explain the Von Fewmann Architecture	03
(d) Criticize the following statement "using a faster processor thip results in a corresponding increase in performance of a computer even if the main memory speed remains the same"	02
(a) Distinguish between RISC and CISC.	$2\frac{2}{3}$
(b) Draw the timing diagram of a Read operation.	03
(c) Write the control steps sequence for the single bus structure for the following instruction	04
(d) Why the MFC signal is needed when reading from or writing to the man memory?	02
(a) Briefly describe MAR, MDR, PC and IR with figure.	05
(b) A disk unit has 12000 tracks. Tracks are divided into 800 sectors and each sectors contains 512 bytes of data. If the diameter of the inner cylinder is 2 inches and outer cylinder is 5 inches then calculate	$4\frac{2}{3}$
I. Total capacity of the disk II. maximum bit density	
III. Format of disk address word (c) What is meant by instruction level parallelisms?	02
(c) What is meant by instruction level parametralist;	
Q4. (a) Write down the pros and cons of micro-programmed control unit over hardware control unit.	03
(b) Given a 32×8 ROM chip with an enable input, show the external comestions necessary to construct	5 2
a 128×8 ROM with four chips and a decoder.	3. 03
(c) What is the purpose of buffer gate in the clock input of a register?	03
SECTION-B	
and the second s	0.4
	04
Q5. (a) What is meant by "data path unit" and "control unit" of a digital system?	32
(b) Draw the model of control unit and states its various inputs.	32,.
(b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization.	1 ²
(b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization.	3 ²
(b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (a) Briefly explain i) Big-endian and ii) Little-endian storage schemes.	$3\frac{2}{3}$.
(b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) Briefly explain i) Big-endian and ii) Little-endian storage schemes.	$3\frac{2}{2}$ 02 02 03
(b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, compared to primary storage medium, access mode	$3\frac{2}{3}$ 02 02 02 pact $4\frac{2}{3}$
(b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, compared to primary storage medium, access mode	$3\frac{2}{3}$ 02 02 02 pact $4\frac{2}{3}$
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, compared to primary storage medium, access mode disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode performance. (d) In control unit organization, what are the functions of control step counter status Flag. 	$3\frac{2}{3}$ 02 02 03 and $4\frac{2}{3}$ and 03
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, compared with respect to primary storage medium, access mode disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode performance. (d) In control unit organization, what are the functions of control step counter status Flag Condition code? 	$3\frac{2}{3}$ 02 02 03 and $4\frac{2}{3}$ and 03
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, comparison of the control of the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common	$3\frac{2}{3}$. 02 02 pact $4\frac{2}{3}$ and 03
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, comparison of the control of the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common memory technologies such as magnetic disk, comparison from the characteristics of some common	$3\frac{2}{3}$. 02 02 pact $4\frac{2}{3}$ and 03
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, comparison to performance. (g) In control unit organization, what are the functions of control step counter, status Flag Condition code? (g) Discuss the data flow of different instruction cycles with neat sketch. (h) Discuss the data flow of different instruction cycles with neat sketch. 	$3\frac{2}{3}$. 02 02 pact $4\frac{2}{3}$ and 03
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, common disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode performance. (d) In control unit organization, what are the functions of control step counter status Flag Condition code? (a) Discuss the data flow of different instruction cycles with near sketch. (b) What are the important advantages of PowerPC processor in comparison to Pentium processor? (b) What are the important advantages of PowerPC processor in comparison to Pentium processor? 	$3\frac{2}{3}$. 02 02 pact $4\frac{2}{3}$ and 03
(b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, comparison disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode performance. (d) In control unit organization, what are the functions of control step counters status Flag Condition code? (a) Discuss the data flow of different instruction cycles with neat sketch. (b) What are the important advantages of PowerPC processor in comparison to Pentium processor? (c) What are the advantages of cache memory over main memory? (d) Evoluin the two-channel DMA controller with necessary figure.	$ \begin{array}{c} 02 \\ 02 \\ 02 \\ 03 \\ 03 \end{array} $ and $ \begin{array}{c} 3\frac{2}{3} \\ 03 \\ 03 \\ 02 \end{array} $
(b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, comparison disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode performance. (d) In control unit organization, what are the functions of control step counters status Flag Condition code? (a) Discuss the data flow of different instruction cycles with neat sketch. (b) What are the important advantages of PowerPC processor in comparison to Pentium processor? (c) What are the advantages of cache memory over main memory? (d) Evoluin the two-channel DMA controller with necessary figure.	$ \begin{array}{c} 02 \\ 02 \\ 02 \\ 03 \\ 03 \end{array} $ and $ \begin{array}{c} 3\frac{2}{3} \\ 03 \\ 03 \\ 02 \end{array} $
 (e) Discuss the incremental processor organization. (e) Discuss the incremental processor organization. (e) Discuss the incremental processor organization. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, common disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode of the control of control step counter. Status Flag Condition code? (d) Discuss the data flow of different instruction cycles with neat sketch. (e) What are the important advantages of PowerPC processor in comparison to Pentium processor? What are the advantages of cache memory over main memory? (d) Explain the two-channel DMA controller with necessary figure. 	$ \begin{array}{c} 02 \\ 02 \\ 02 \\ 03 \\ 03 \end{array} $ and $ \begin{array}{c} 3\frac{2}{3} \\ 03 \\ 03 \\ 02 \end{array} $
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, comparison to performance. (g) In control unit organization, what are the functions of control step counters status Flag Condition code? (h) Discuss the data flow of different instruction cycles with neat sketch. (h) What are the important advantages of PowerPC processor in comparison to Pentium processor? (e) What are the advantages of cache memory over main memory? (d) Explain the two-channel DMA controller with necessary figure. (a) What is a zont by tetch phase and execution phase? What will be happened inside the CPU after the controller instruction? 	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, commodisk ROM, metal oxide semiconductor with respect to primary storage medium, access mode performance. (d) In control unit organization, what are the functions of control step counter status Flag Condition code? (a) Discuss the data flow of different instruction cycles with neat sketch. (b) What are the important advantages of PowerPC processor in comparison to Pentium processor? (c) What are the advantages of cache memory over main memory? (d) Explain the two-channel DMA controller with necessary figure. (a) What is meant by tetch phase and execution phase? What will be happened inside the CPU after execution of an instruction? (a) What is meant by tetch phase and execution phase? What will be happened inside the CPU after execution of an instruction? (d) Discuss the dafferent ways of implementing a multiprocessor system. 	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, commodisk ROM, metal oxide semiconductor with respect to primary storage medium, access mode performance. (d) In control unit organization, what are the functions of control step counter status Flag Condition code? (a) Discuss the data flow of different instruction cycles with neat sketch. (b) What are the important advantages of PowerPC processor in comparison to Pentium processor? (c) What are the advantages of cache memory over main memory? (d) Explain the two-channel DMA controller with necessary figure. (a) What is meant by tetch phase and execution phase? What will be happened inside the CPU after execution of an instruction? (a) What is meant by tetch phase and execution phase? What will be happened inside the CPU after execution of an instruction? (d) Discuss the dafferent ways of implementing a multiprocessor system. 	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (c) Write the characteristics of some common memory technologies such as magnetic disk, competence of the control of the control	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) Write the differences between EPROM and FLASH memory? (f) Write the characteristics of some common memory technologies such as magnetic disk, common disk ROM, metal oxide semiconductor with respect to primary storage medium, access mode performance. (d) In control unit organization, what are the functions of control step counter, status Flag Condition code? (a) Discuss the data flow of different instruction cycles with neat sketch. (b) What are the important advantages of PowerPC processor in comparison to Pentium processor? (c) What are the advantages of cache memory over main memory? (d) Explain the two-channel DMA controller with necessary figure. (a) What is meant by tetch phase and execution phase? What will be happened inside the CPU after execution of an instruction? (b) Discuss about the different ways of implementing a multiprocessor system. (c) Consider 4 instructions to execute (1, 12, 13, 14) and each instruction has 4 parts (F, D, O, W). (c) Consider 4 instructions to execute (1, 12, 13, 14) and each instruction has 4 parts (F, D, O, W). (d) Pincling 	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$
 (b) Draw the model of control unit and states its various inputs. (c) Discuss the incremental processor organization. (d) Briefly explain i) Big-endian and ii) Little-endian storage schemes. (e) What are the differences between EPROM and FLASH memory? (c) Write the characteristics of some common memory technologies such as magnetic disk, competence of the control of the control	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$

Heaven's Links	BILL	CA
Rajshahi Um B Sc. Engineer 3 3rd Year 6th Semester Expresses Exp		
Department f Computer Science and Technology		
Department of Company of Militation 2012		
Course No. C5 603 Course Title: Computer Architecture Full A 4ks: 70 Time: THREE (03) James		¥
Full N arks: 70 Time: THREE (03) looms	1	
Allswei StA Questione taking mun ne		
The questions are of equal value.		
Use separate answer script for each section		
SECTION A		
O1(a) Criticize the following at the	Marky	
With figure briefly describe Man ain memory speed remains the same		
(c) What is meant by fetch phase and execution phase? What happen inside the CPU after execution of a suppose you are a serious phase?	04	
	n 05	
(a) What is RAID? Describe the problem of PAID.	ι	
(b) Are RAID level 0.4 and 0+1 true 2 1 (16) in a	02%	
(c) Which RAID level should be imple and the control of the contro	05	
i). Required minimum of two disk ii) Mirroring concept and iii. One write or two reads are possible at the same time.	0.3	
(a) From the following pin configuration doign a memory chip.		
Output pins 103	04	
(b) Design a ROM chin which can be a seem to the contract of t		
changed/erased data from a specific position and need 13V to change it current state.	05	
(4(a) Explain DMA operation during I/O.	0235	
(b) Consider 6 instructions to execute (1. 1. 1. 1.	02%	
Assuming each part takes 2 clock cycl and the delay of each buffer is 0 clock i). Non-pipelining architecture	06	
(i). Pipelining architecture and		
iii). Supper-pipeliring architecte c.	•	
SECTION B	03	
Q5(a) Analyze the data dependencies among Le following statement		
7 11. Edda 11, 1024	*34	
S2:Load R2, M(10)		
S3: Add R1, R2 S4: Store M(1024), R1		
S4: Store M(1024), R1 S5: Store M((R2)), 10 4		
Answer the following questions:		
 i). Draw a dependency graph to show all the dependencies. ii). Are there any resource dependencies if only one copy of each functional unit is available in the 	03	
CDITO	04	
(15) Sketch a suitable bus architecture for the following arrangements: Available devices: Processor, Memory, Faster devices, Slower devices Available buses: local buses, high-speed bus, expansion bus.	043	
Available buses: local buses, high-speed bus, expansion bus. A memory location contains the pattern 00101100. What does this pattern represent when interpreted as a binary number? What does it represent as an ASCII code?	′03 ³ 3	
Write a program that can evaluate the expression $A*B+C*D$ in a single accumulator processor. Assume	04	
(v) Design than mentory arrangement for the following program.	04	
Move N, Ri Move # Num, Ri		
Clear R0		
Loop Add (R2), R0		
Increment R2		
Decrement R1		
Branch > 0 Loop		
Draw an input interface circuit connecting a keyboard to an asynchronous bus.	03	
(b) Briefly explain with necessary figure the two-channel DMA controller. (c) What is meant by control signals? Draw the model of the control unit and discuss its different inputs and	03	
outputs 5-568	0235	
(d) Prove that the multiplication of two n-digit numbers in base B gives a product of no more than 2n digits Describe the optical and magnetic read/write mechanism with necessary diagram 4 - 203	03	
Describe the optical and magnetic read/write mechanism with necessary diagram 3-203 Define micro operations. Write down the sequence of events of different instruction cycle 5-556/75	03	
(c) Describe the internal processor organization with necessary data paths and control singles.	03	
What is meant by I/O interface? Discuss different parts of I/O interface for an input device. Scanned by CamScanner	023	
I S AANNAA NI I AMSAANNAR		

	The Well A was it is out Mit to	
	Rajshabi Iniversity of Engineering & Technology	
	B.Sc. Enginering to year Comester a min don 2013	
	Departs and of Computer Science & Lugin Computer & Lugin Compu	
	Course no: C* & 603 Course Fitle: Coursater A shreefure Full narks, 70 Fune: Three (0.4) how 5	
	Turning to the turner to the total to the to	
	N.B. Answer six questions, taking the ee from one election.	
	The questions are of equal value	
	Use separate answer script for each section.	
	Q1 (a) Define pipeline processing (19 c 100)	
	Q1. (a) Define pipeline processing (ipe (in the control of the con	2
	(b) Write in detail about variou addressing modes, 525	1 1
	(c) List the steps involved in the instruction execution.	3
	(d) What is the need for reduce instruction thip, \(\sigma \).	2
	(a) What is the need to restaur	2
	A Difference of Economic Returns the bandwind material annulation and the	-
	Q2. (a) What are the difference between the hardwired control organization and micro	0 3
	programmed control organi ution. 5 9	2
	(b) What are the differences between main memory and virtual memory?	
	(c) Draw and explain the opera on of a 6-transistor SRAM cell	4
	(d) How many bits does cache have, if cache block size is I word and it contains 8 blocks, 2	2 1 4
	bit tag and 1 bit valid bit.	
	Q3 (a) Explain the virtual memory basis with page mapping.	1 7
	Q3 (a) Explain the virtual memory basis with page mapping. (b) Illustrate the characteristics of some common memory technologies.	4
	(b) Illustrate the characteristics of some common memory technologies.	3
	(c) What is DVD? Why DVD stores more data than CD-ROM? Explain.	.,
	The the concept of pipelining in CPU design.	4
	Q4. (a) Explain the concept of pipelining in CPU design.	3
	(b) Compare the RISC and CISC architecture. (c) Explain the need for having a hierarchical memory organization and explain the hierarchy	1 1
	(c) Explain the need for having a hierarchical memory organization	
	in detail with a block diagram. 6 12 SECTION-12	1 1
•	(ent of 15/1550) ()	3
	(15 (a) Convert the following high level mist uses single address instruction services	
	Q5. (a) Convert the following high level instruction into corresponding set of features. Instruction carried out by a machine that uses single address instruction scheme. Instructions available are: Load, Sub, Add. Mpy, Mov, Store A = A + B + D	
	instruction carried out by a machine that the instruction carried out by a machine that the instructions available are: Load, Sub, Add. Mpy, Mov, Store $A = A + B + D$ $A = A + B + D$ $A = A + B + D$	3
	moles of zero address instructions with their purposes the following control	5
	instruction carried out by a magnitude instruction available are: Load, Sub, Add. Mpy, Mov, Store Instructions available are: Load, Sub, Add. Mpy, Mov, Store A = A + B + D A = A + B + D Give three examples of zero address instructions with their purposes. (b) Give three examples of zero address instructions with their purposes. (c) Given single bus organization of process complements with only the following control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignals. How many bits will be occupied for these control signals in a single microsignal signals. How many bits will be occupied for these control signals in a single microsignal signals. How many bits will be occupied for these control signals in a single microsignal signals.	0
	Given single bus organization of process control signals in a single signals. How many bits will be occupied for these control signals in a single signals. How many bits will be occupied for these control signals in a single signals. How many bits will be occupied for these control signals in a single signals in a single signals in a single signals. How many bits will be occupied for these control signals in a single signals in a single signals in a single signals. How many bits will be occupied for these control signals in a single signals in a single signals. How many bits will be occupied for these control signals in a single signals in a single signals in a single signal sign	1129
1	signals. How many consideration scheme? FCOC, Solar Solar C. Solar	2
11	mistriction in the AND MARIN MORAGE Fruit Fluid Version of Universal Serial Dus	3 3
	17 h de differences between USB 2.0 and USB 3.0 and US	3
	signals. How many bits will be occupied for the signals. How many bits will be occupied for the signals. How many bits will be occupied for the signals. How many bits will be occupied for the signals. How many bits will be occupied for the signals. Proof ADD, Poor A	13
	(USD): Explained for Warding"? Why is it used by the second problems of	5-
	(b) What is "Operand for Warding"? Why is it used in problems of example. 5. 96.7 (c) What is branch folding? Can the use of an instruction queue get mid off all problems of What is branch folding? Can the use of an instruction queue get mid off all problems of the parally in case of pipelining? Why? CAL.	
	example. S. A. Granthe use of an instruction queue. (a) What is branch folding? Can the use of an instruction queue. (b) What is branch folding? Why? C.A. (Can the use of an instruction queue. (b) What is branch folding? Can the use of an instruction queue.	
		3 2
	7. (a) Explain DMA operation during I/O. (b) Describe a scenario where RAID 1 is buffer to implement instead of RAID 0.5. (c) Explain 'straight line sequencing' or instruction with example.	$\frac{3^{2}}{3}$
0	7 (a) Explain DMA operation during 170.	5
Q.	Becaribe a scenario where RAID 1 is butter to implement	3
	(c) Explain straight inte sequent of Harvard	$3^{\frac{2}{3}}$
	there is it different from the concept of	
00	What is Von-Neumann architecture and how is it divides in a computer? Draw a block Architecture. (b) Why priority assignment is required for interrupting devices in a computer? Draw a block Why priority assignment is required for interrupting devices in a computer? Draw a block Why priority assignment is required for interrupt priority scheme using individual interrupt-request	3
Qo.	Architecture. (b) Why priority assignment is required for interrupting devices in a computer. Diameters which will be a computer of the compu	
,	(b) Why priority assignment is required for interrupt priority scheme using individual interrupt	
	diagram of implementation of interrupt production	5
	and acknowledgement	
	and acknowledgements acknowledgements acknowledgements acknowledgements acknowledgements acknowledgements acknowle	
(c	Briefly explain the followings: (i) capacitive and resistive touch screen (ii) HDMI port.	
	(i) capacitive and	

amouting (iii) VGA

Dept. of CSE, RUET (4 cycle C day- 7^{th} April, 2016)

Class Test: 1

Q.1 What is the basic difference between Computer Architecture and Organization? (06)

Q.2 Write in brief about the main components including functions of Computer Architecture. (14)

Dept. of CSE, RUET// 26th April 2016

Class Test: 2

CSE 603

Time: 20 Min Marks: 20

Q.1 How does an ALU work? Discuss Booth's Algorithm with necessary example. (04+08)

Q.2 Discuss the problem of sign magnitude representation. Define (i) 1's compliment and (ii) 2's compliment with necessary example. (04+04)

Dept. of CSE, RUET

Class Test: 3

CSE 603

Time: 20 Min Marks: 20

Q.1 What do you mean by the Instruction pipelining? Write the advantages and disadvantages of it. (06+04)

Q. 2 Explain (i) RISC and (ii) CISC. Which one (RISC or CISC) is better and why? (05+05)

67-cy
6-cylain parallel computing. Write basic computations with serial computing. (3+5).

2. Briefly desertibe (1) SISD (1) SIMD (1) MIMD (4+3=12).